

# **DIE COMPACTED TIPS** PROCESS DESCRIPTION



**PRODUCTION FLOW CHART** METALOR TECHNOLOGIES ELECTROTECHNICS FRANCE

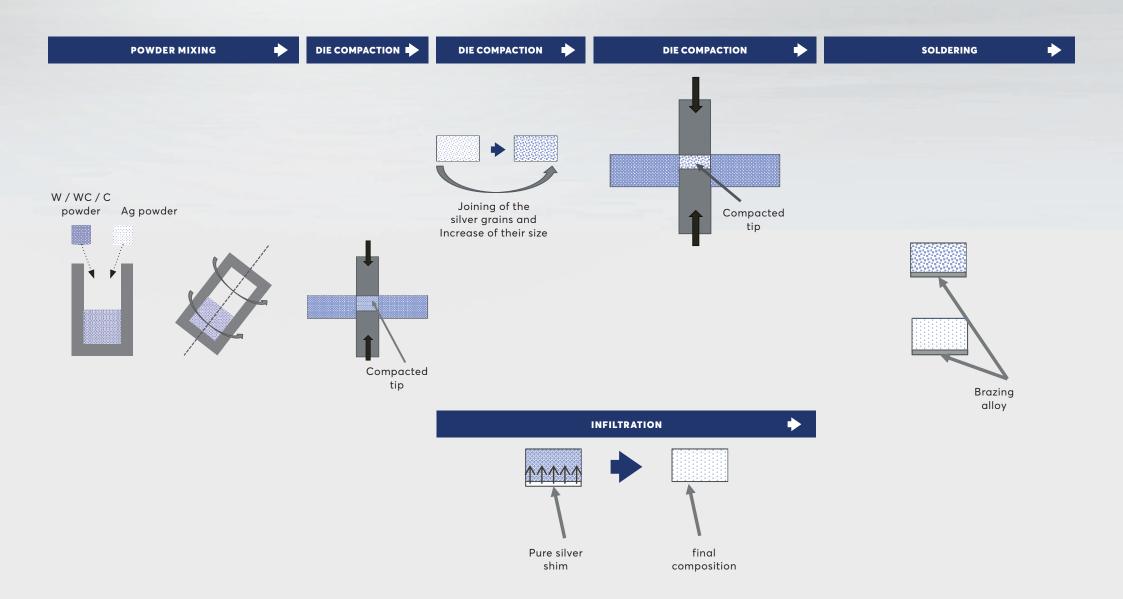




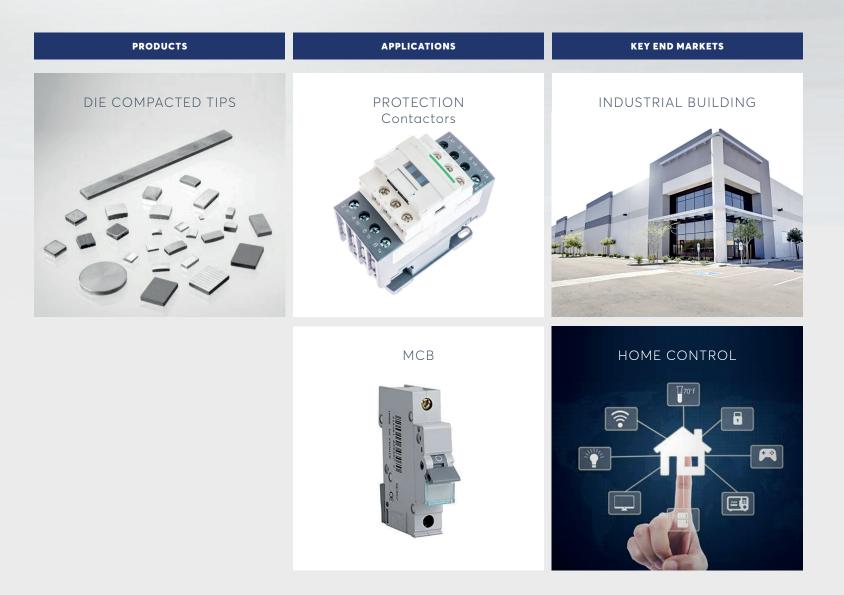
### DIE COMPACTED TIPS:

PROCESS FLOW

## 







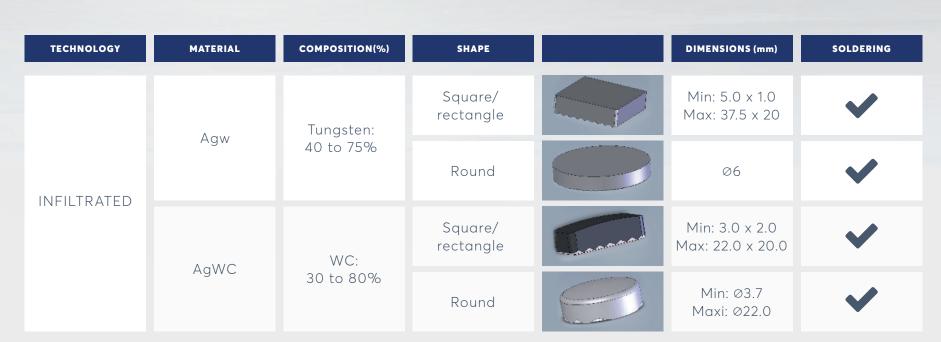
#### **DIE COMPACTED TIPS:** TYPE OF PRODUCT



TECHNOLOGY	MATERIAL	COMPOSITION(%)	SHAPE		DIMENSIONS (mm)	SILVER UNDERLAYER (BI-COMPACTION)	SOLDERING
SINTERED/ CALIBRATED	AgC	Graphite: 3 and 5%	Square/ rectangle		Min: 3.2 x 3.2 Max: 25.0 x 12.5	×	×
			round		Min: Ø3.0 Max: Ø5.0	×	*
	AgW	Tungsten: 50%	Square/ rectangle		8.7 x 5.0	~	~
			round	×	×	×	×
	AgWC	WC 20 and 80%	Square/ rectangle		Min: 7.0 x 4.0 Max: 15.0 x 12.0	~	~
			round	×	×	×	×
	AgNi	Ni 10 to 30%	Square/ rectangle		Min: 10.0 x 6.5 Max: 24.0 x 18.5	×	~
			round	0	Ø3.2	×	~

## DIE COMPACTED TIPS:

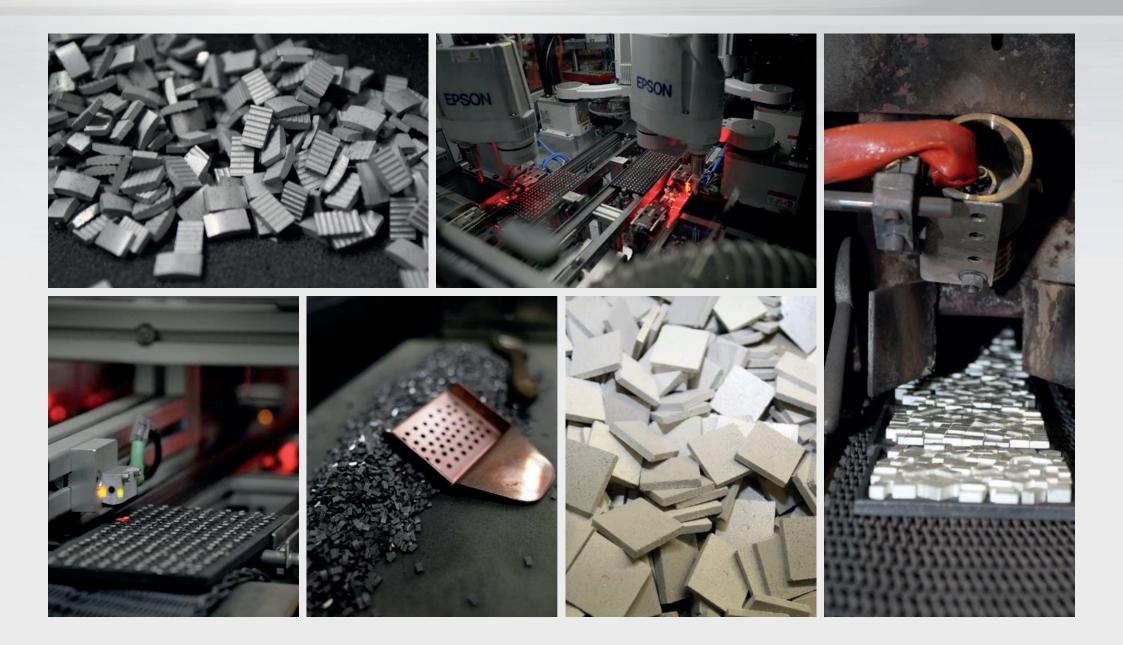
TYPE OF PRODUCT



All of these information are based on our current production. For further information or outer dimension, please contact METALOR

#### **DIE COMPACTED TIPS:** PROCESS PICTURES





#### **DIE COMPACTED TIPS:**

PERFORMANCE VS TECHNOLOGY

# METALOR® STANAKA

<ul> <li>Standard process by METALOR</li> <li>Competitiveness for high volumes</li> <li>Different type of technologies</li> </ul>	PROS	CONS	
- Competitiveness for high volumes			
	- Standard process by <b>METALOR</b>	- not for all material composition	
- Different type of technologies	- Competitiveness for high volumes		
	- Different type of technologies		

# METALOR® CTANAKA



